

## Searches for User *zel-arini* (Count = 2877)

Queries 5655 through 5704.

Find

S #	Updt	Database	Query	Time	Comme
<u>S2877</u>	<u>U</u>	USPT	3754896.pn.	2004-04-08 12:43:33	
<u>S2876</u>	<u>U</u>	USPT	4002463.pn.	2004-04-08 12:42:26	
<u>S2875</u>	<u>U</u>	USPT	5595345.pn.	2004-04-08 09:09:20	
<u>S2874</u>	<u>U</u>	TDBD,DWPI,JPAB,EPAB,USOC,USPT,PGPB WAFER!		2004-04-07 15:22:53	
<u>S2873</u>	<u>U</u>	TDBD,DWPI,JPAB,EPAB,USOC,USPT,PGPB WAFERASSEMBLY!		2004-04-07 15:22:01	
<u>S2872</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	pick-up wafer same particles	2004-04-07 15:09:34	
<u>S2871</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	pick-up wafer	2004-04-07 15:08:49	
<u>S2870</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water and ((inert gas) or nitrogen) and immersing and removing and maintaining	2004-04-07 13:25:02	
<u>S2869</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water and ((inert	2004-04-07 13:24:45	

			gas) or nitrogen) and immersing and removing	
<u>S2868</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water and ((inert gas) or nitrogen) and immersing	2004- 04-07 13:24:32
<u>S2867</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water and ((inert gas) or nitrogen)	2004- 04-07 13:24:03
<u>S2866</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$) and water	2004- 04-07 13:23:11
<u>S2865</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping and ((organic solvent\$) or alcohol\$)	2004- 04-07 13:22:37
<u>S2864</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer and stripping	2004- 04-07 13:21:56
<u>S2863</u>	<u>U</u>	PGPB,USPT,EPAB,JPAB,DWPI,TDBD	(post etch) and (metal lines) and wafer	2004- 04-07 13:21:34
<u>S2862</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon contamin\$) and (soil or sand or earth) and (hydrogen peroxide) and disproportion\$ and flotation	2004- 04-07 09:37:44
<u>S2861</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon contamin\$) and (soil or sand or earth) and (hydrogen peroxide) and disproportion\$ and floatation	2004- 04-07 09:37:24
<u>S2860</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon contamin\$) and (soil or sand or earth) and (hydrogen peroxide) and disproportion\$	2004- 04-07 09:35:40
<u>S2859</u>	<u>U</u>	PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD	(hydrocarbon	2004-